

Digital Power Amplifier R2S15102NP

10Wx2ch(SE)/20Wx1ch(BTL) Digital Audio Power Amplifier

1. Outline

R2S15102NP is a Digital Power Amplifier IC developed for TV.

R2S15102NP can realize maximum Power 10W × 2ch

(VD = 24V, THD = 10%, SE) at 8 Ω load.

It is possible to replace from the conventional analog amplifier system to the digital amplifier system easily.

2. Feature

- High Output Power (THD=10%) without external Heat Sink
(note) the thermal pad is soldered the thermal pad with the printed-circuit board directly.

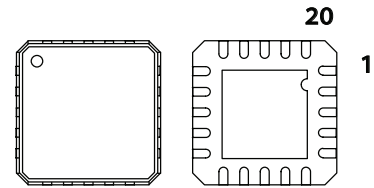
Recommended Power Condition

SE operation mode : 10Wx2ch (VD=24V) at 8 Ω

BTL operation mode: 20Wx1ch (VD=18V) at 8 Ω

- The RENESAS original circuits realize high power efficiency, low noise and low distortion characteristics.
- Pop sound Less
- Built-in protection function
(Over Current, Over Temperature and Under Voltage)
- Built-in Mute and Stand-by function

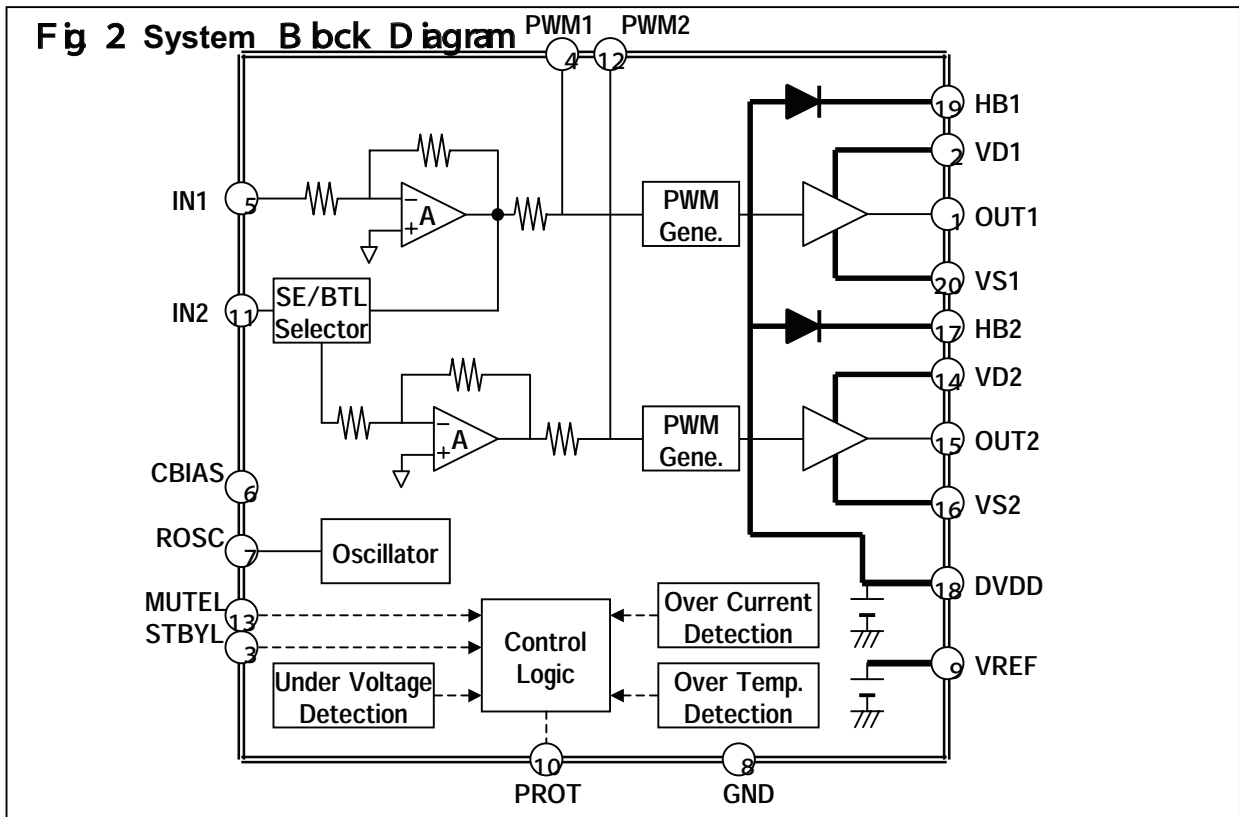
Fig 1 Package



20pin QFN
Body : 6 x 6 mm
Lead pitch : 0.8 mm

3. Operating Condition

- Recommended Power supply voltage : from 11V to 25V
- Recommended Speaker Impedance : from 4 to 8Ω



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5. Pin Configuration(Table.1)

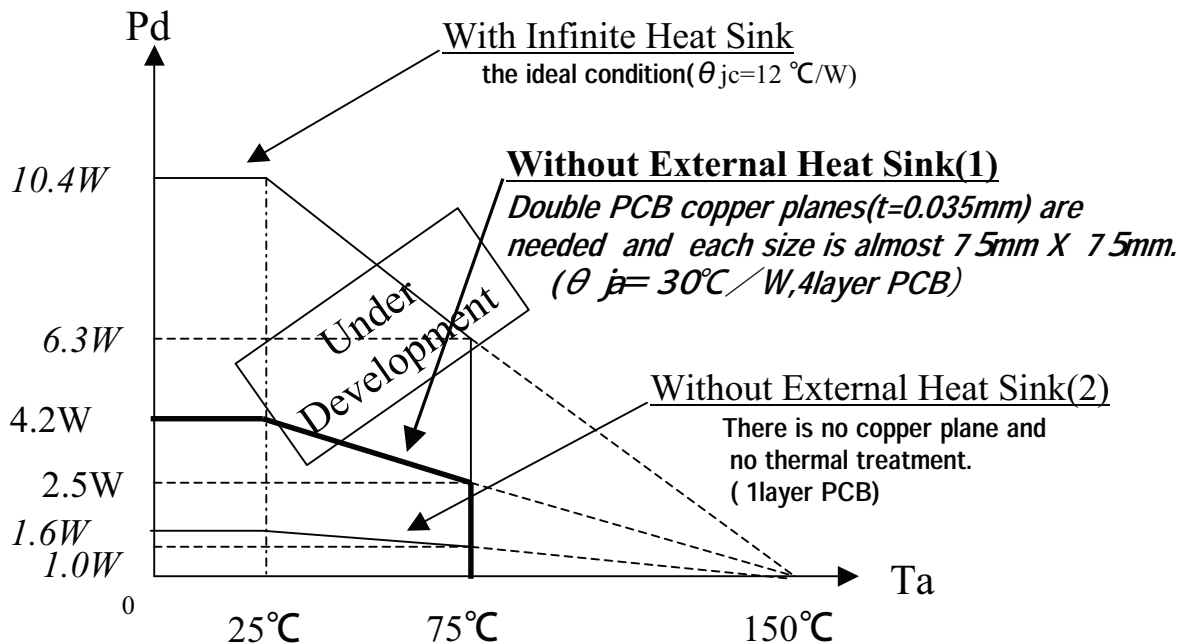
No.	NAME	I/O	Description	
1	OUT1	O	Power Output pin #1	
2	VD1	—	Power supply pin for power output stage #2	
3	STBYL	I	Stand-by control pin. When this is “L”, circuit current is reduced. There is the pull-down resistor:50Kohm(typ.).	
4	PWM1	I	PWM input pin #1 (for phase compensation)	
5	IN1	I	Analog input #1. The gain is depended on the external resistance .	
6	CBIAS	I/O	A capacitor is connected so that it may not be influenced of power supply change(Ripple Filter).	
7	ROSC	I	Control pin for PWM carrier frequency	
8	GND	—	GND pin for analog block	
9	VREF	I/O	Capacitor connection pin for analog block reference voltage source	
10	PROT	O	Protection Timer pin. At protection mode,the output becomes “L”-level. (The timing capacitor is connected)	
11	IN2	I	SE operation	Analog input #2(as same as IN1)
		I	BTL operation	When this is connected to DVDD pin via the resister, Reversed signal of OUT1 is output to OUT2.
12	PWM2	I	PWM input pin#2 (for phase compensation)	
13	MUTEL	I	Mute control pin. When this is “L”, it becomes mute status.	
14	VD2	—	Power supply pin for power output stage #2	
15	OUT2	O	Power Output pin #2	
16	VS2	—	Ground pin for power output stage #2	
17	HB2	I/O	Capacitor connection pin for bootstrap	
18	DVDD	O	Built-in power supply pin for internal digital block.	
19	HB1	I/O	Capacitor connection pin for bootstrap #1	
20	VS1	—	Ground pin for power output stage #1	

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6. Absolute Maximum Rating(Table.2)

Symbol	Parameter	Condition	Value	Unit
VD max	Maximum VD Voltage	VD1,VD2 pin voltage	27	V
HB max	Maximum HB Voltage	HB1、HB2 pin voltage	40	V
Pd	Power dispassion	Ta = 25°C :See Fig.3	4.2	W
θ_{ja}	Thermal Resistance	See Fig.3	30	°C/W
Tj	Junction temperature	Maximum Temperature	150	°C
Ta	Operating ambient temperature	Temperature range	-20~75	°C
Tstg	Storage temperature	Temperature range	-40~150	°C

Fig.3 Thermal De-rating(on PCB: printed-circuit board):Size 75mm x 75mm

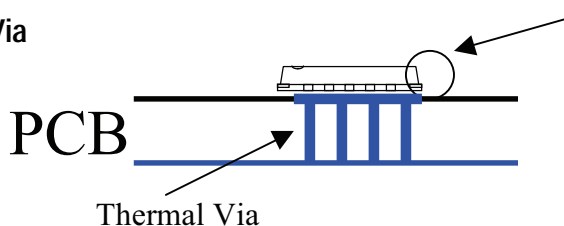


(NOTE)

PCB pattern design for high effective thermal conductivity

(1)The exposed die pad is directly soldered with the printed-circuit board pattern .

(2)Thermal Via



(caution)

There are side expositions of the die pad at corners of the package.

(The die pad is grounded.)

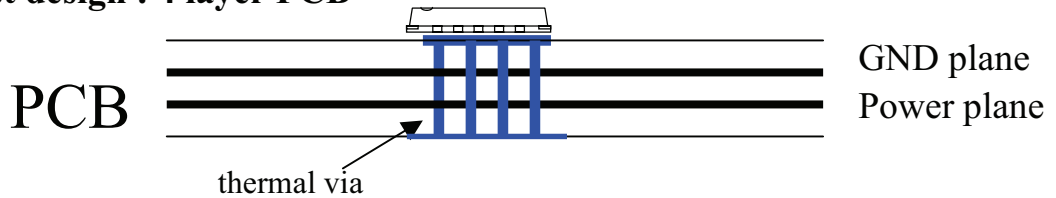
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Consideration about the PCB design

The Power dissipation at 10Wx2ch(SE) or 20Wx1ch(BTL) is estimated almost 2W. It has enough margin, designing the PCB at $\theta_{ja}=30^{\circ}\text{C}/\text{W}$.

(1)PCB basic design (copper plane)

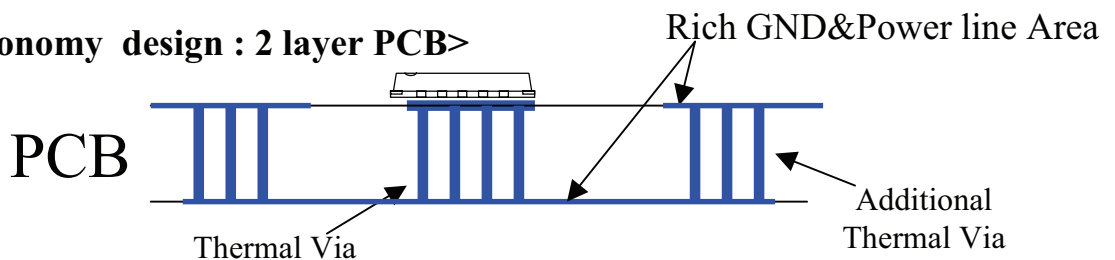
<the best design : 4 layer PCB>



<PCB size estimation >

10Wx2ch: 75mm x 75mm

<the economy design : 2 layer PCB>



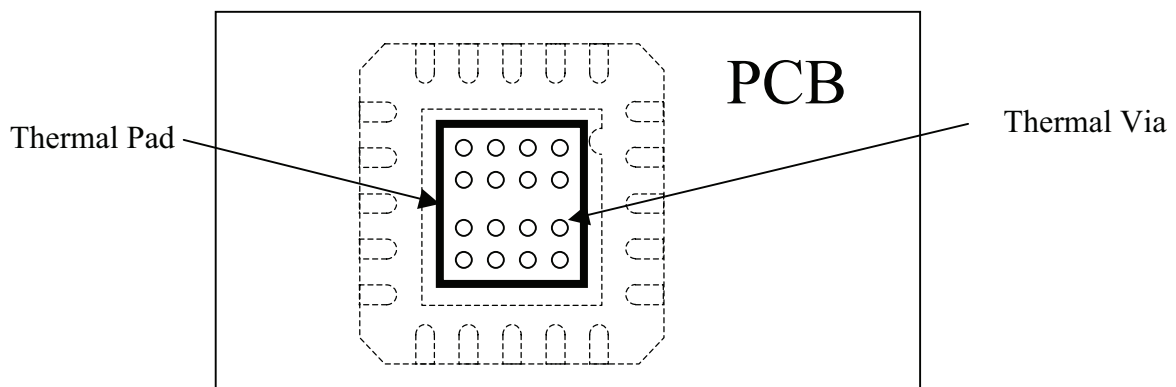
The GND&Power line total area size is also equal to the above GND&Power line total area size of the 4layer PCB.

<PCB size estimation >

10Wx2ch: $(75 + \alpha)$ mm x $(75 + \alpha)$ mm

(2)PCB Thermal Pad

The exposed die pad is directly soldered with the printed-circuit board pattern .



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7. Recommended Operating condition(Table.3)

Symbol	Parameter	Condition	MIN	TYP	MAX	Unit
VD	Supply Voltage	VD1,VD2 pin voltage	11	-	25	V
VH	Control voltage of high level	STBYL、MUTEL	2	-	5	V
VL	Control voltage of low level	STBYL、MUTEL	0	-	0.8	V
fosc	Carrier Frequency	R= 33 k Ω	300	400	600	kHz

- (note)
- STBYL: High level:normal operation Low level:Stand-by
 - MUTEL:High level:normal operation Low level:Mute
 - The carrier frequency can be changed by the resistance at Pin#.7 .

8. Electronic Characteristics(Table.4)

(Unless otherwise noted, Ta=25°C, VD=24V, Carrier Frequency=400kHz, f=1kHz,SE operation)

Symbol	Parameter		Condition	MIN	TYP	MAX	Unit
IVD	Circuit Current		No Signal	TBD	28	TBD	mA
			MUTE	TBD	-	TBD	mA
			Stand-by	-	-	10	uA
VDPR	Detection Voltage		VD under-voltage	TBD	9.8	TBD	V
TPR	Protection Temperature		Thermal Shut-down	-	150	-	°C
TRL	Release Temperature		Thermal Shut-down	-	120	-	°C
IPR	Protection Current		Output over-current	-	6	-	A
Pomax	Maximum output power	at SE	THD=10%、VD=24V、RL=8 Ω	TBD	10	-	W/ch
		at BTL	THD=10%、VD=18V、RL=8 Ω	TBD	20	-	W
THD	Total Harmonic Distortion		Po=1W	-	0.1	TBD	%
No	Output Noise level		A-Weighted filter	-	(100)	TBD	uVrms
Eff	Power Efficiency	at SE	Po=10+10W	TBD	93	-	%
		at BTL	Po=20W	TBD	89	-	%
Mute	Mute Attenuation			TBD	80	-	dB
PSRR	Ripple Rejection Ratio		dVD=100mVrms,f=100 Hz	TBD	50	-	dB

9. Application Examples

Fig.4 SE operation mode(10Wx2ch)

(note)

“R for GND” ‘s are for the evaluation only and not needed actually.

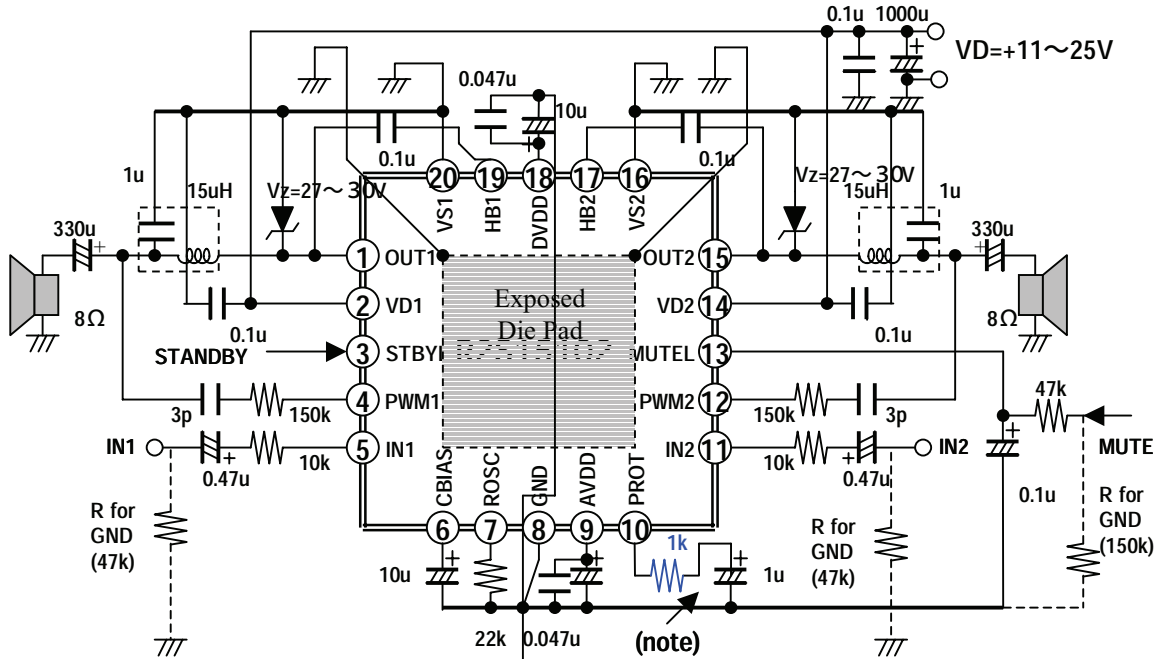
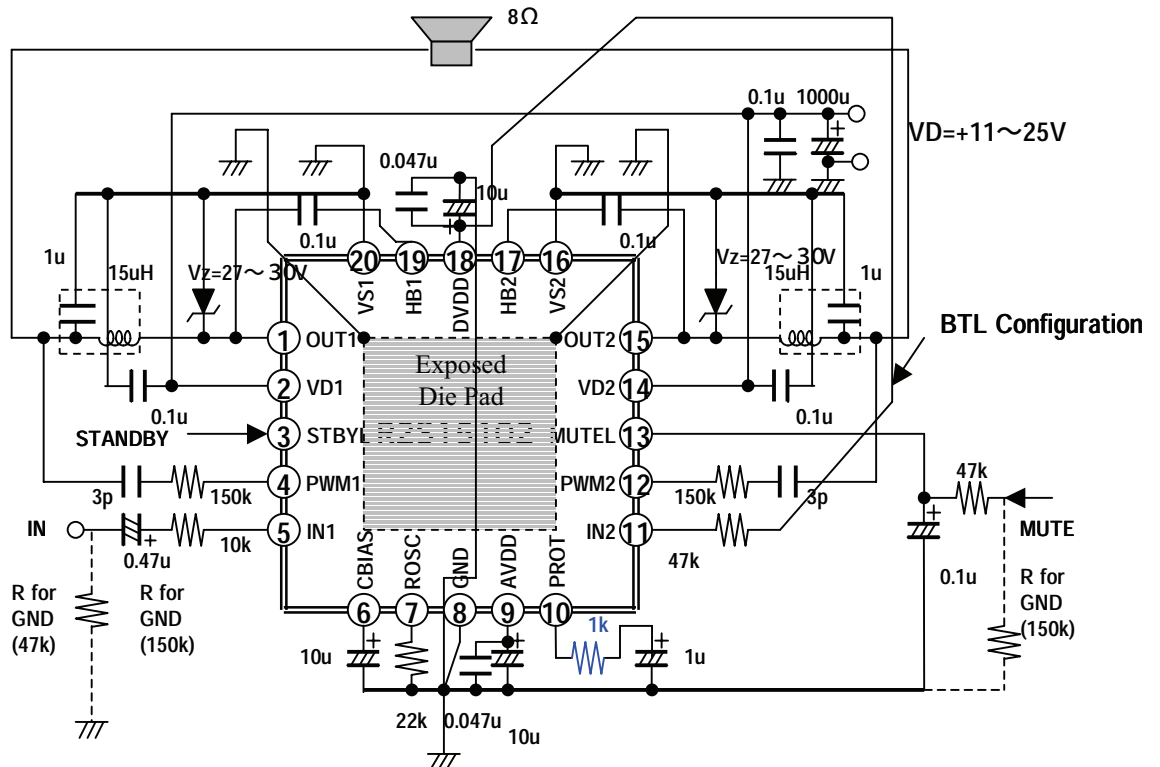


Fig.5 BTL operation mode (20W)



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Fig.6 BTL operation mode(20W) with PWM direct input

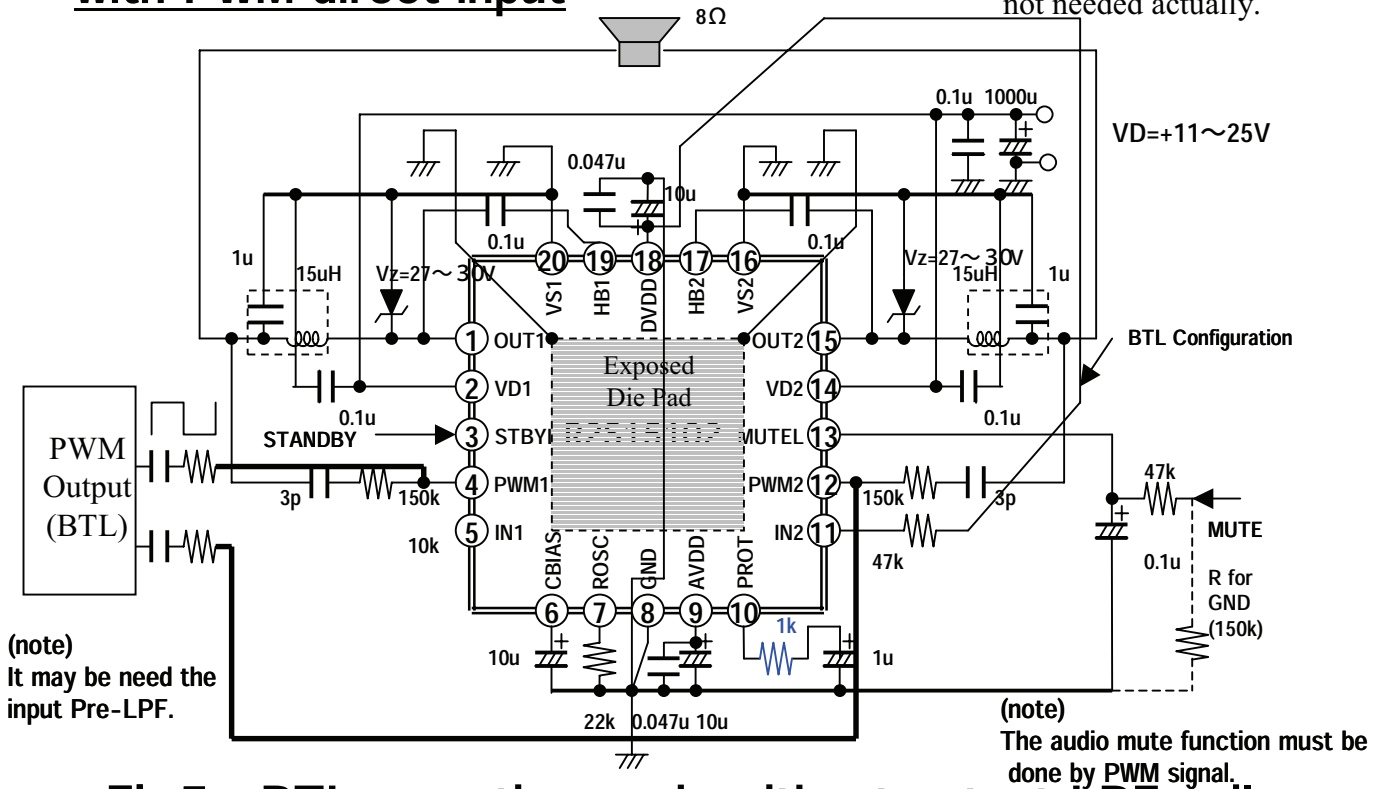


Fig.7 BTL operation mode without output LPF coil

If this speaker lines is very short, the LPF coil is not needed.

